

Abstract

LOGIC DIE AND OTHER COMPONENTS EMBEDDED IN BUILD-UP LAYERS

Embodiments of the present disclosure are directed towards package assemblies, as well as methods for forming package assemblies and systems incorporating package assemblies. A package assembly may include a substrate comprising a plurality of build-up layers, such as BBUL. In various embodiments, electrical routing features may be disposed on an outer surface of the substrate. In various embodiments, a primary logic die and a second die or capacitor may be embedded in the plurality of build-up layers. In various embodiments, an electrical path may be defined in the plurality of build-up layers to route electrical power or a ground signal between the second die or capacitor and the electrical routing features, bypassing the primary logic die.

(Figure 1)